

Sub C17  
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covering the package substrate, the integrated circuit die, and the interposer with a heat spreader to form an internal chamber; filling the internal chamber with a cooling fluid, wherein the cooling fluid contacts a region between the interposer and the integrated circuit die.

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10. (Amended) A method of forming an integrated circuit package comprising:  
attaching an interposer to a package substrate;  
attaching an integrated circuit die to the interposer;  
covering the package substrate, the integrated circuit die, and the interposer with a heat spreader to form an internal chamber;  
filling the internal chamber with a cooling fluid by pumping cooling fluid through a via in the package substrate and sealing the via after the internal chamber is filled.

11. (Amended) A method of forming an integrated circuit package comprising:  
attaching an interposer to a package substrate;  
attaching an integrated circuit die to the interposer;  
covering the package substrate, the integrated circuit die, and the interposer with a heat spreader to form an internal chamber;  
filling the internal chamber with a cooling fluid by pumping cooling fluid through an inlet and sealing closed the inlet when the filling is complete.

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A3  
27. (Amended) An integrated circuit package comprising:

an integrated circuit die housed within a chamber, wherein the  
integrated circuit die includes an active region;

a cooling fluid filling the chamber and in contact with the active  
region of the integrated circuit die.